# **TF410**



http://onsemi.com

# **N-Channel JFET** 40V, 50 to $130\mu A$ , 0.11mS, USFP

### **Applications**

· Impedance conversion, infrared sensor applications

### **Features**

- · Ultrasmall package facilities miniaturization in end products: 1.0mm×0.6mm×0.27mm (max 0.3mm)
- Small IGSS: max -500pA (VGSS= -20V, VDS=0V)
- Small Ciss: typ. 0.7pF (VDS= 10V, VGS=0V, f=1MHz)
- · Halogen free compliance

### **Specifications**

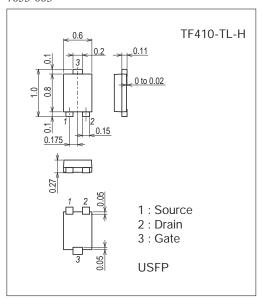
### Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Conditions	Ratings	Unit
Drain-to-Source Voltage	VDSS		40	V
Gate-to-Drain Voltage	V <sub>GDS</sub>		-40	V
Gate Current	IG		10	mA
Drain Current	ID		1	mA
Allowable Power Dissipation	PD		30	mW
Junction Temperature	Tj		150	°C
Storage Temperature	Tstg		-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

### **Package Dimensions**

unit: mm (typ) 7055-003



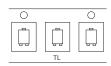
### **Product & Package Information**

• Package : USFP

• JEITA, JEDEC : -

• Minimum Packing Quantity : 10,000 pcs./reel

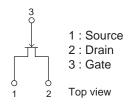
### Packing Type: TL



# Marking



### **Electrical Connection**

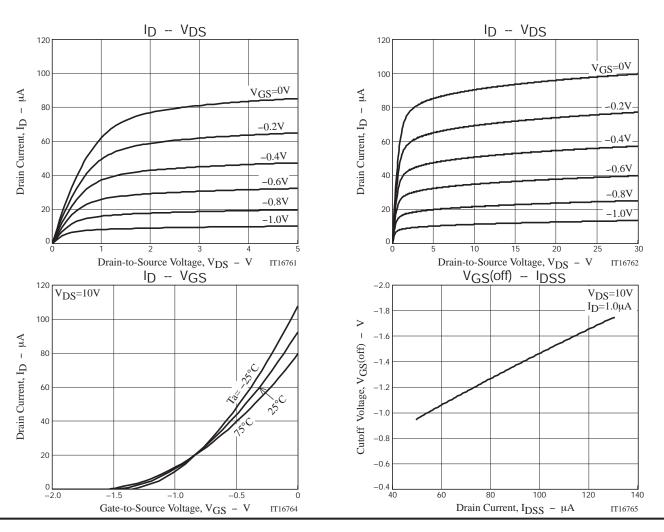


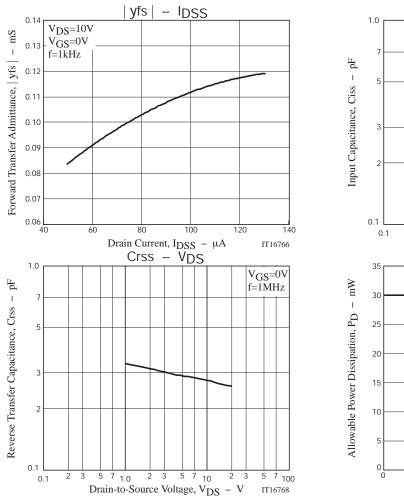
### Electrical Characteristics at Ta=25°C

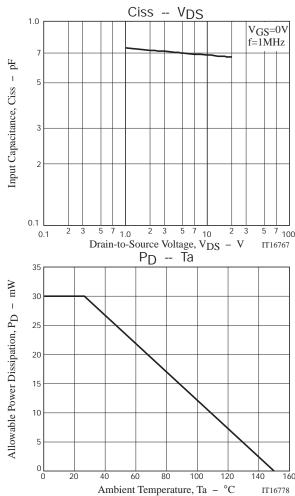
Parameter	Symbol	Conditions	Ratings			Unit
	Syllibol	Conditions	min	typ	max	OTIIL
Gate-to-Drain Breakdown Voltage	V(BR)GDS	IG=-10μA, VDS=0V	-40			V
Gate-to-Source Leakage Current	IGSS	V <sub>GS</sub> =-20V, V <sub>DS</sub> =0V			-500	рА
Cutoff Voltage	V <sub>GS</sub> (off)	V <sub>DS</sub> =10V, I <sub>D</sub> =1μA		-1.4	-4.0	V
Drain Current	IDSS	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V	50		130	μΑ
Forward Transfer Admittance	yfs	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, f=1kHz	0.05	0.11		mS
Input Capacitance	Ciss	VDS=10V, VGS=0V, f=1MHz		0.7		pF
Reverse Transfer Capacitance	Crss	VDS=10V, VGS=0V, I=1IVIHZ		0.3		pF

### **Ordering Information**

Device	Package	Shipping	memo	
TF410-TL-H	USFP	10,000pcs./reel	Pb Free and Halogen Free	





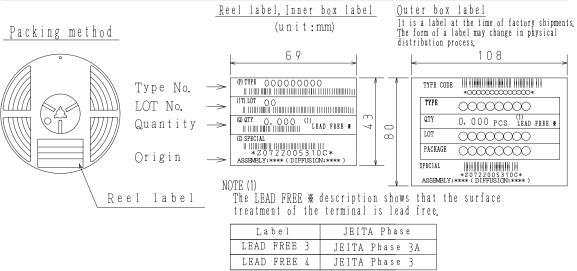


### Taping Specification

### TF410-TL-H

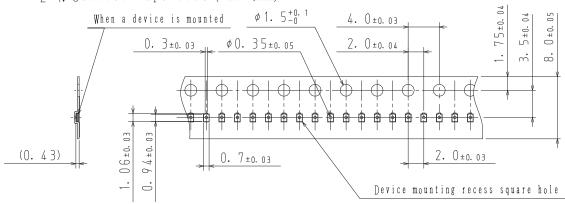
### 1. Packing Format

Package Name	Carrier Tape	Maximum Number of devices contained (pcs)			Packing	g format		
	Туре	Reel	Inner box	Outer box	Inner $BOX(C-1)$	Outer BOX (A-7)		
USFP	USFP	10,000	50,000	300,000	5 reels contained	6 inner boxes contained		
					Dimensions:mm (external)	Dimensions:mm (external)		
					183×72×185	440×195×210		

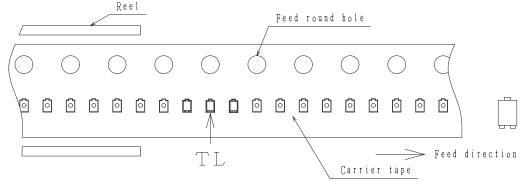


### 2. Taping configuration

2-1. Carrier tape size (unit:mm)



2-7. Device placement direction



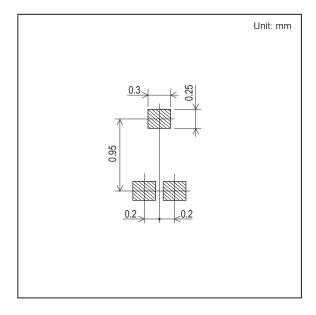
Those with one electrode terminal on the feed hole side·····TL

## **Outline Drawing**

TF410-TL-H

# Mass (g) Unit (0.0005) mm 0.640.04 0.1140.05 0.1140.05 0.1150.08 0.1550.

### Land Pattern Example



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